SMD16PL-TP-FS
SMD110PL-TP-FS

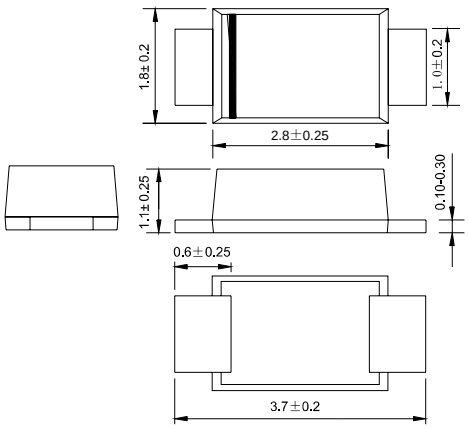
1.0A Surface Mount Schottky Barrier Rectifiers

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Metal silicon junction,majority carrier conduction
- Low power loss,high efficiency
- High forward surge current capability
- High temperature soldering guaranteed: 260℃/10 seconds
- Compliant to RoHS Directive 2011/65/EU
- Compliant to Halogen-free

Package outline

SOD-123FL



Dimensions in inches and (millimeters)

Mechanical data

- **Case**: JEDEC SOD-123FL molded plastic body
- **Terminals**: Plated axial leads, solderable per MIL-STD-750, Method 2026
- **Polarity**: Color band denotes cathode end
- **Mounting Position**: Any

Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	*SYMBOLS*	SMD16PL-TP-FS	SMD110PL-TP-FS	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	60	100	V
Maximum RMS voltage	V_{RMS}	42	70	V
Maximum DC blocking voltage	V_{DC}	60	100	V
Maximum average forward rectified current at T_L(see fig.1)	$I_{(AV)}$	1.0		A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30.0		A
Maximum instantaneous forward voltage at 1.0A	V_F	0.70	0.85	V
Maximum DC reverse current T_A=25℃	I_R	0.5	0.1	mA
at rated DC blocking voltage T_A=100℃		10.0	5.0	
Typical junction capacitance (NOTE 1)	C_J	110		pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	92		°C/W
Operating junction temperature range	T_J,	-55 to +150		°C
Storage temperature range	T_{STG}	-55 to +150		°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2.P.C.B. mounted with 2.0x2.0″(5.0x5.0cm) copper pad areas

Rating and characteristic curves

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

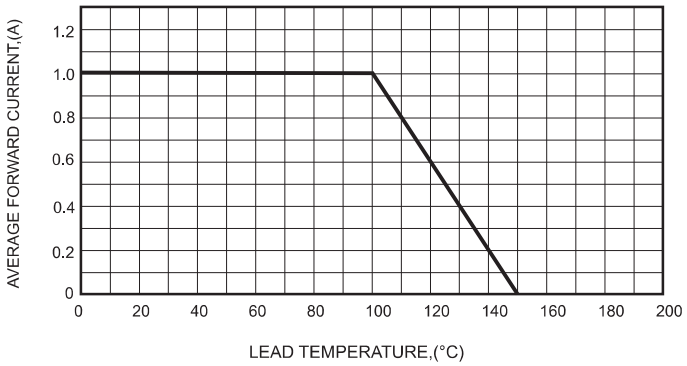


FIG.2-TYPICAL FORWARD CHARACTERISTICS

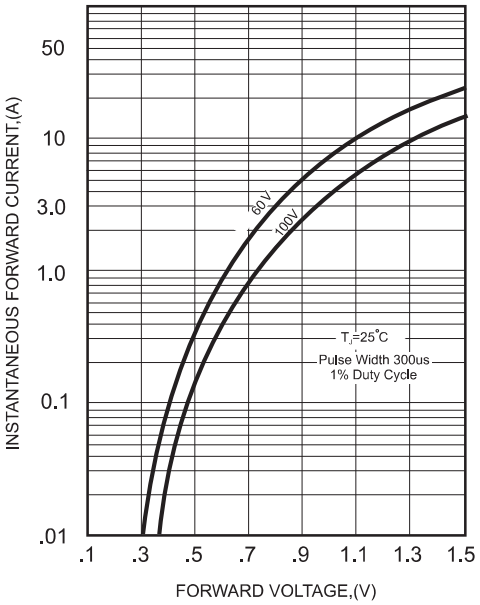


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

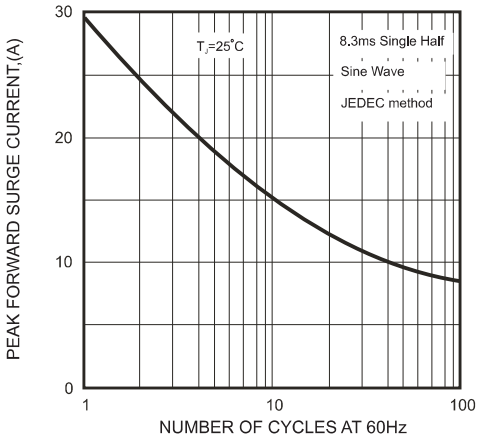


FIG.4-TYPICAL JUNCTION CAPACITANCE

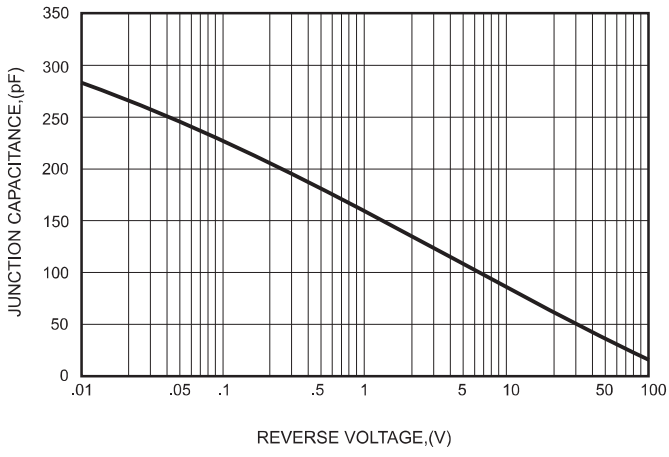
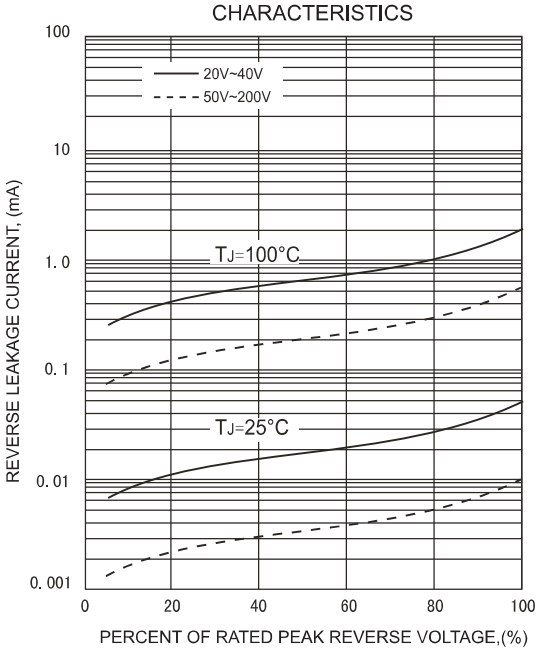


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



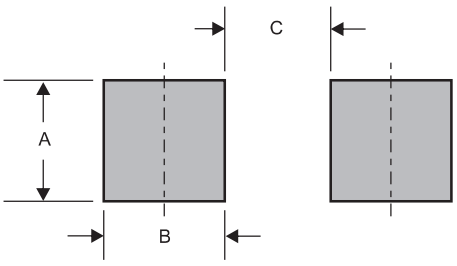
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
SMD16L-TP-FS	K16
SMD110PL-TP-FS	K110

Suggested solder pad layout

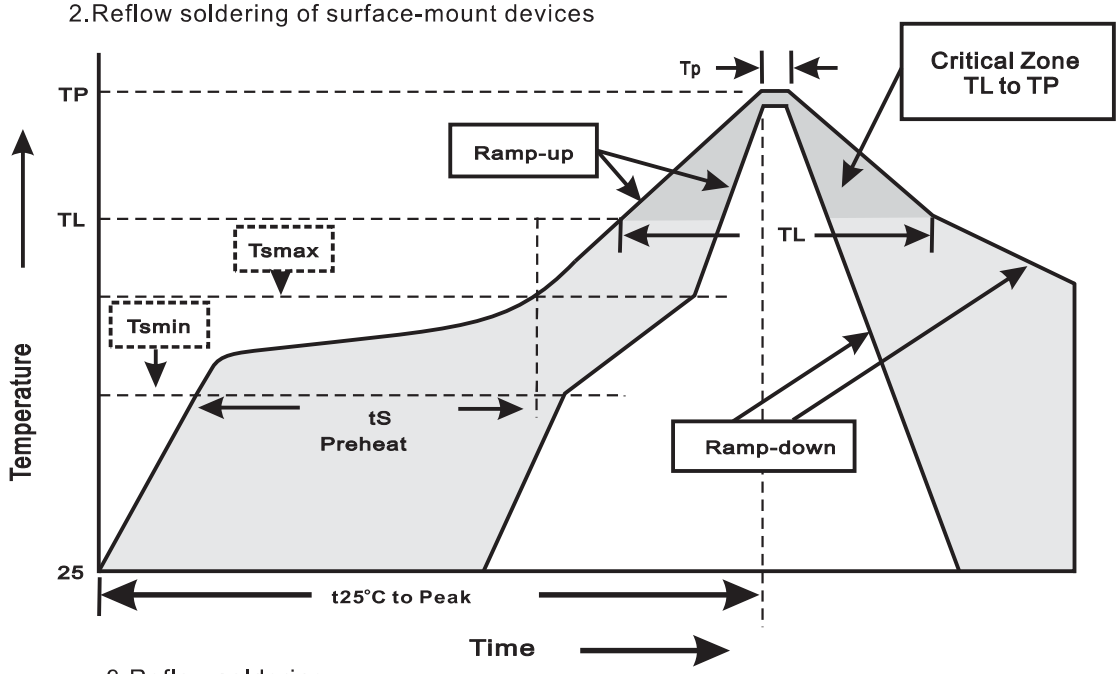


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123FL	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(t_s)	 150°C 200°C 60~120sec
Tsmax to T_L -Ramp-upRate	 <3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	 217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes